

MOSFET - N-Channel, POWERTRENCH[®], DUAL COOL[®]

40 V, 420 A, 0.56 mΩ

FDMT80040DC

General Description

This N-Channel MOSFET is produced using onsemi's advanced POWERTRENCH process. Advancements in both silicon and DUAL COOL package technologies have been combined to offer the lowest $r_{DS(on)}$ while maintaining excellent switching performance by extremely low Junction-to-Ambient thermal resistance.

Features

- Max $r_{DS(on)}$ = 0.56 mΩ at $V_{GS} = 10\text{ V}$, $I_D = 64\text{ A}$
- Max $r_{DS(on)}$ = 0.9 mΩ at $V_{GS} = 6\text{ V}$, $I_D = 47\text{ A}$
- Advanced Package and Silicon Combination for Low $r_{DS(on)}$ and High Efficiency
- Next Generation Enhanced Body Diode Technology, Engineered for Soft Recovery
- Low Profile 8x8 mm MLP Package
- MSL1 Robust Package Design
- 100% UIL Tested
- This Device is Pb-Free, Halide Free and RoHS Compliant

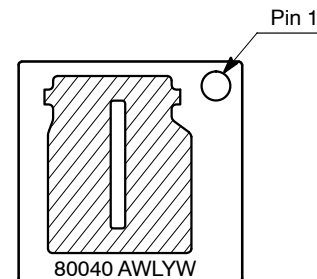
Typical Applications

- OringFET/Load Switching
- Synchronous Rectification
- DC-DC Conversion



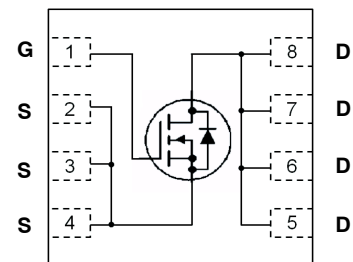
Top Bottom
TDFNW8 8.3x8.4, 2P
(DUAL COOL, OPTION 2)
CASE 507AR

MARKING DIAGRAM



80040 = Device Code
A = Assembly Location
WL = Wafer Lot Code
Y = Year Code
W = Work Week Code

ELECTRICAL CONNECTION



N-Channel MOSFET

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 2 of this data sheet.

FDMT80040DC

MOSFET MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Unit
V_{DS}	Drain to Source Voltage	40	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current –Continuous $T_C = 25^\circ\text{C}$ (Note 5)	420	A
	–Continuous $T_C = 100^\circ\text{C}$ (Note 5)	265	
	–Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	64	
	–Pulsed (Note 4)	2644	
E_{AS}	Single Pulse Avalanche Energy (Note 3)	2773	mJ
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	156	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	3.2	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to $+150$	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Top Source)	1.6	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Bottom Drain)	0.8	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	38	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	81	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1i)	15	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1j)	21	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1k)	9	

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Reel Size	Tape Width	Shipping [†]
80040	FDMT80040DC	TDFNW8 8.3x8.4, 2P, (DUAL COOL, OPTION 2)	13"	13.3 mm	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

FDMT80040DC

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0 V	40	–	–	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25°C	–	21	–	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 32 V, V _{GS} = 0 V	–	–	10	μA
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	–	–	±100	nA

ON CHARACTERISTICS

V _{GS(th)}	Gate to Source Threshold Voltage	V _{GS} = V _{DS} , I _D = 250 μA	2.0	2.7	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25°C	–	–9	–	mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 64 A	–	0.44	0.56	mΩ
		V _{GS} = 6 V, I _D = 47 A	–	0.63	0.9	
		V _{GS} = 10 V, I _D = 64 A, T _J = 125°C	–	0.66	0.84	
g _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 64 A	–	278	–	S

DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz	–	18650	26110	pF
C _{oss}	Output Capacitance		–	5540	7760	pF
C _{rss}	Reverse Transfer Capacitance		–	304	1210	pF
R _g	Gate Resistance		0.1	1.8	3.6	Ω

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	V _{DD} = 20 V, I _D = 64 A, V _{GS} = 10 V, R _{GEN} = 6 Ω	–	63	101	ns
t _r	Rise Time		–	62	100	
t _{d(off)}	Turn-Off Delay Time		–	101	162	
t _f	Fall Time		–	43	69	
Q _{g(TOT)}	Total Gate Charge	V _{GS} = 0 V to 10 V, V _{DD} = 20 V, I _D = 64 A	–	241	338	nC
		V _{GS} = 0 V to 6 V, V _{DD} = 20 V, I _D = 64 A	–	149	209	
Q _{gs}	Gate to Source Charge	V _{DD} = 20 V, I _D = 64 A	–	76	–	nC
Q _{gd}	Gate to Drain "Miller" Charge		–	35	–	nC

DRAIN-SOURCE DIODE CHARACTERISTICS

V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.6 A (Note 2)	–	0.67	1.1	V
		V _{GS} = 0 V, I _S = 64 A (Note 2)	–	0.77	1.2	
t _{rr}	Reverse Recovery Time	I _F = 64 A, di/dt = 100 A/μs	–	94	151	ns
Q _{rr}	Reverse Recovery Charge		–	219	351	nC

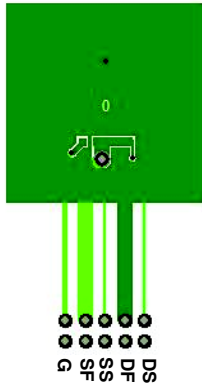
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Top Source)	1.6	$^{\circ}\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Bottom Drain)	0.8	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	38	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	81	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1c)	26	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1d)	34	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1e)	14	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1f)	16	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1g)	26	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1h)	60	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1i)	15	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1j)	21	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1k)	9	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1l)	11	

NOTES:

- $R_{\theta JA}$ is determined with the device mounted on a FR-4 board using a specified pad of 2 oz copper as shown below. $R_{\theta CA}$ is determined by the user's board design.



a) 38°C/W when mounted on a 1 in² pad of 2 oz copper.



b) 81°C/W when mounted on a minimum pad of 2 oz copper.

- Still air, $20.9 \times 10.4 \times 12.7$ mm Aluminum Heat Sink, 1 in² pad of 2 oz copper
 - Still air, $20.9 \times 10.4 \times 12.7$ mm Aluminum Heat Sink, minimum pad of 2 oz copper
 - Still air, $45.2 \times 41.4 \times 11.7$ mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in² pad of 2 oz copper
 - Still air, $45.2 \times 41.4 \times 11.7$ mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper
 - .200FPM Airflow, No Heat Sink, 1 in² pad of 2 oz copper
 - .200FPM Airflow, No Heat Sink, minimum pad of 2 oz copper
 - .200FPM Airflow, $20.9 \times 10.4 \times 12.7$ mm Aluminum Heat Sink, 1 in² pad of 2 oz copper
 - .200FPM Airflow, $20.9 \times 10.4 \times 12.7$ mm Aluminum Heat Sink, minimum pad of 2 oz copper
 - .200FPM Airflow, $45.2 \times 41.4 \times 11.7$ mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in² pad of 2 oz copper
 - .200FPM Airflow, $45.2 \times 41.4 \times 11.7$ mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper
- Pulse Test: Pulse Width < 300 μs , Duty cycle < 2.0%.
 - E_{AS} of 2773 mJ is based on starting $T_J = 25^{\circ}\text{C}$; N-ch: $L = 3$ mH, $I_{AS} = 43$ A, $V_{DD} = 40$ V, $V_{GS} = 10$ V. 100% test at $L = 0.3$ mH, $I_{AS} = 93$ A.
 - Pulsed Id please refer to Figure 11 SOA graph for more details.
 - Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

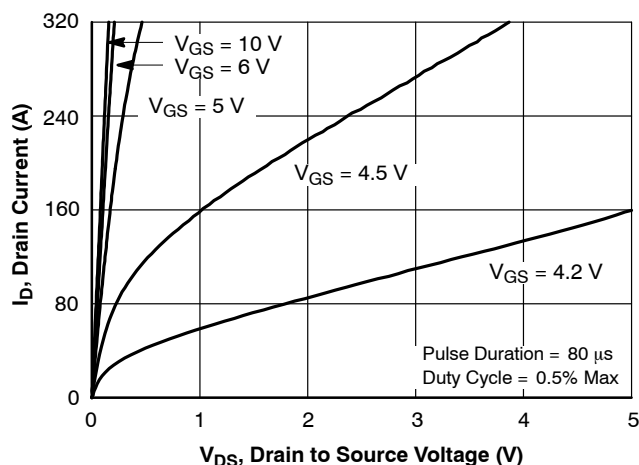


Figure 1. On Region Characteristics

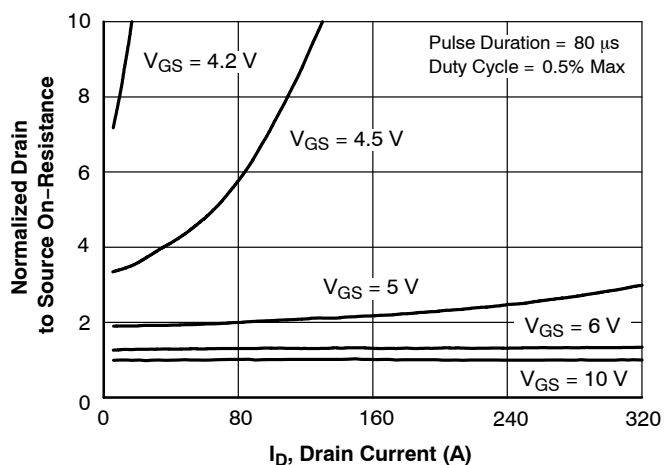


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

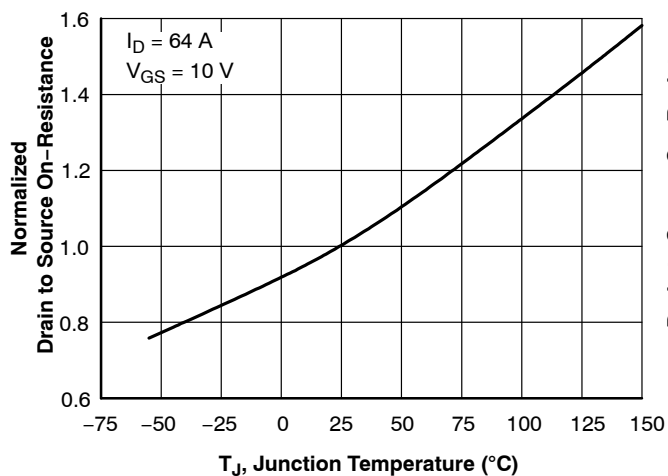


Figure 3. Normalized On Resistance vs. Junction Temperature

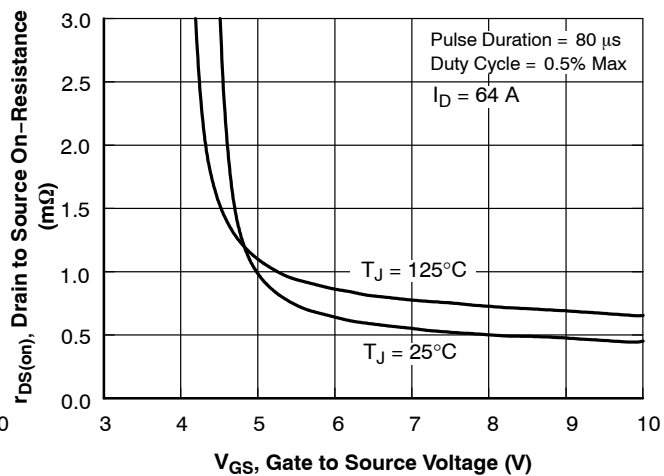


Figure 4. On-Resistance vs. Gate to Source Voltage

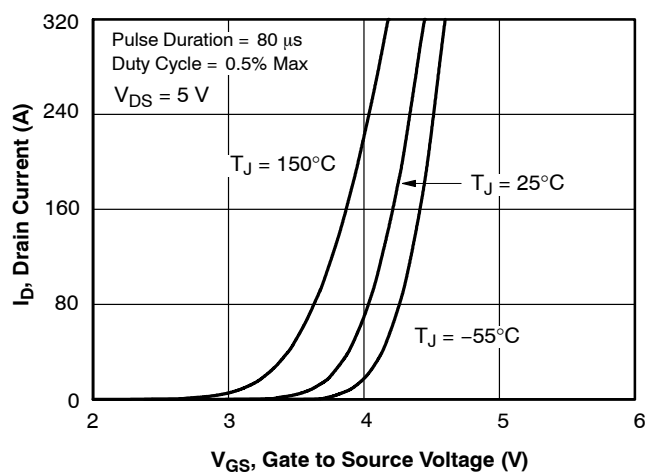


Figure 5. Transfer Characteristics

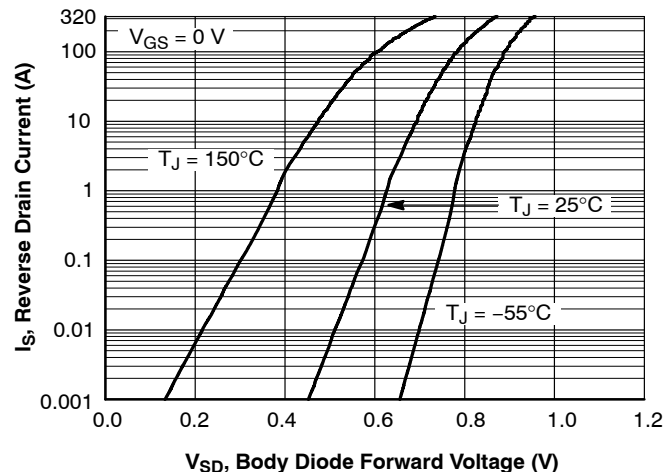


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

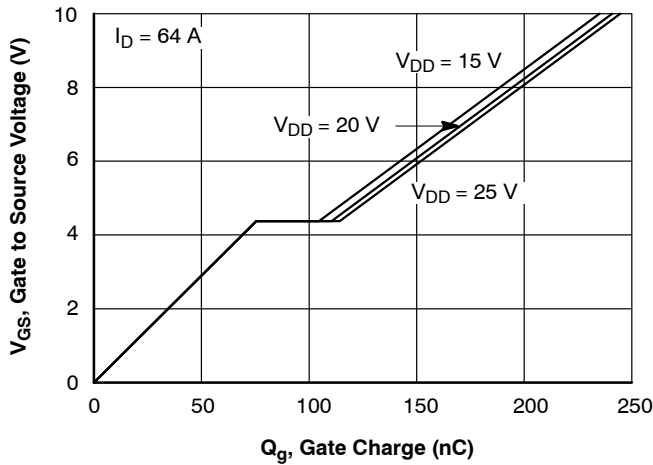


Figure 7. Gate Charge Characteristics

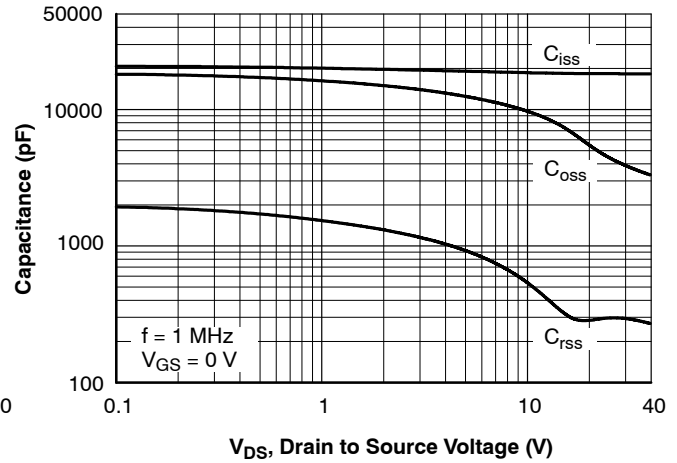


Figure 8. Capacitance vs. Drain to Source Voltage

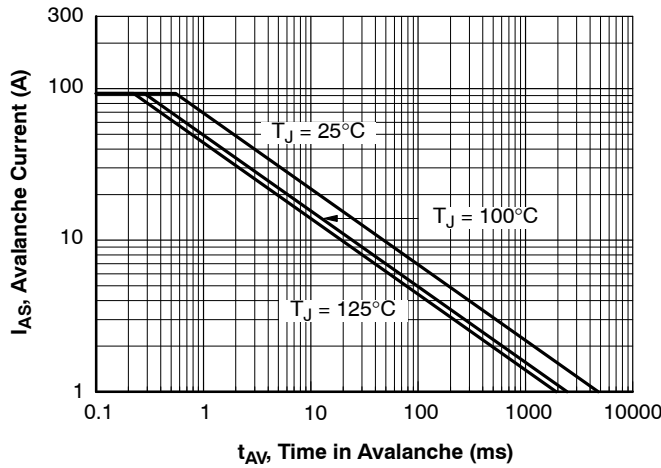


Figure 9. Unclamped Inductive Switching Capability

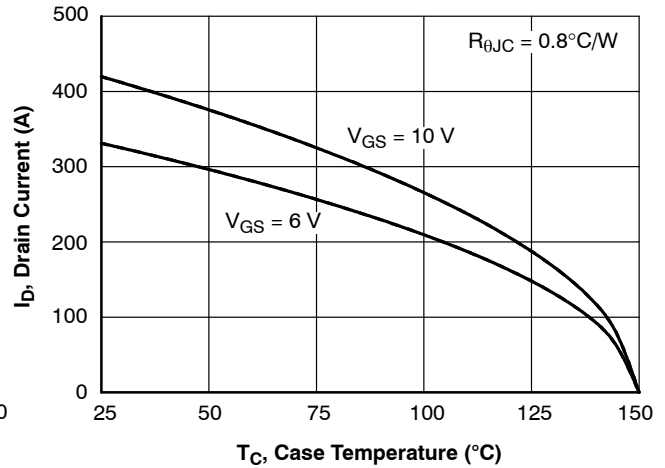


Figure 10. Maximum Continuous Drain Current vs Case Temperature

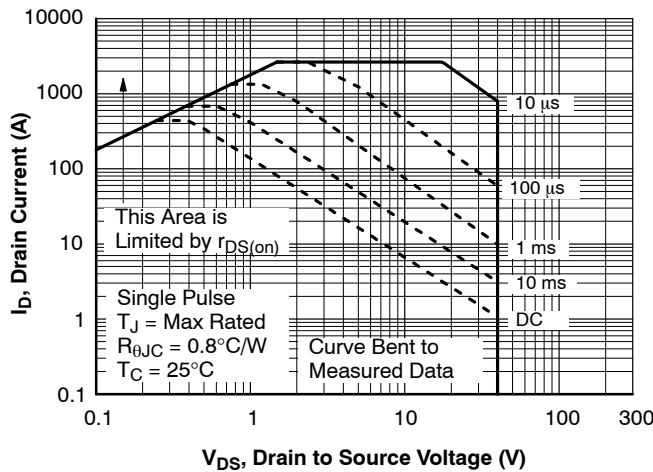


Figure 11. Forward Bias Safe Operating Area

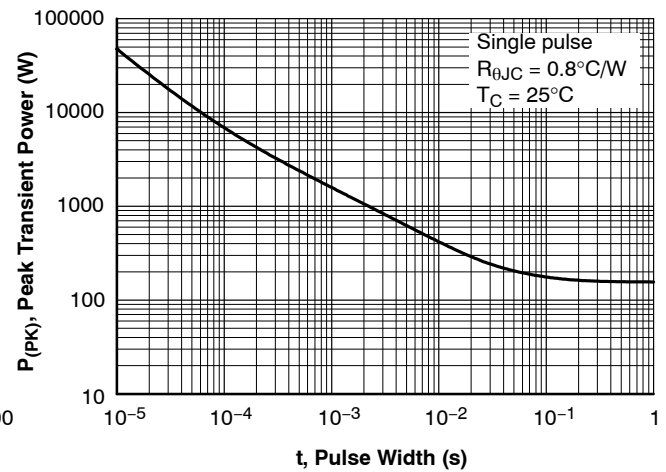


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

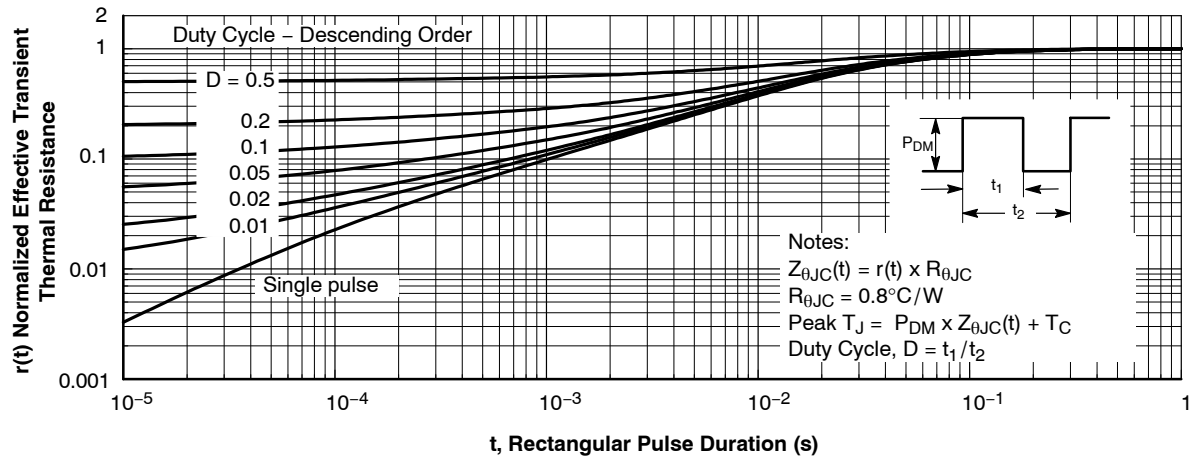
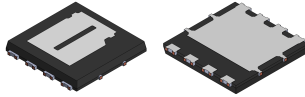
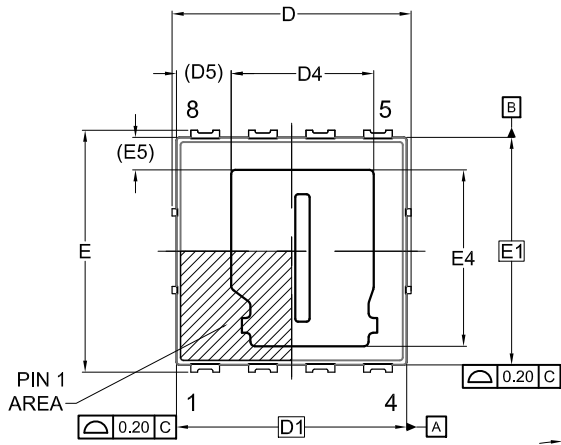


Figure 13. Junction-to-Case Transient Thermal Response Curve

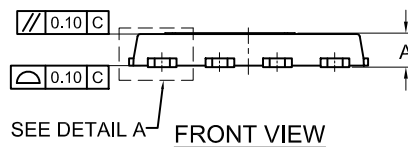


TDFNW8 8.30x8.40x0.92, 2.00P
CASE 507AR
ISSUE C

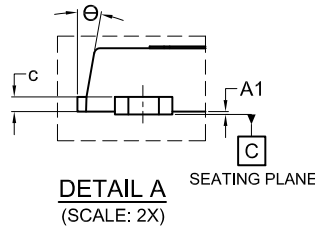
DATE 29 MAY 2024



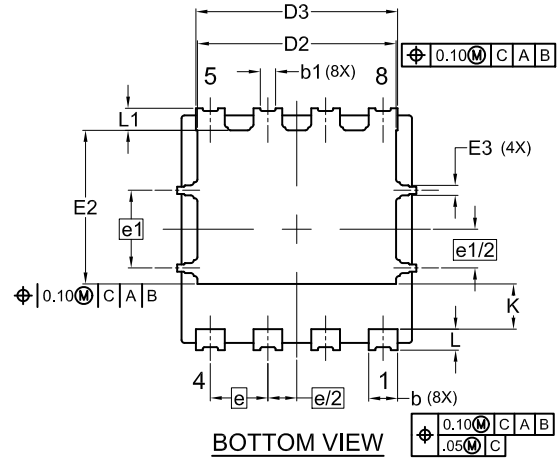
TOP VIEW



FRONT VIEW



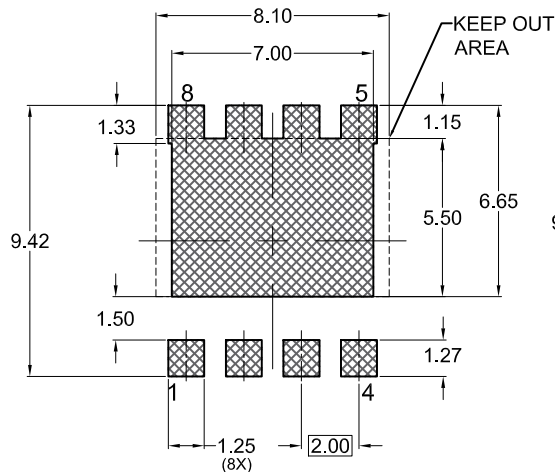
DETAIL A
(SCALE: 2X)



BOTTOM VIEW

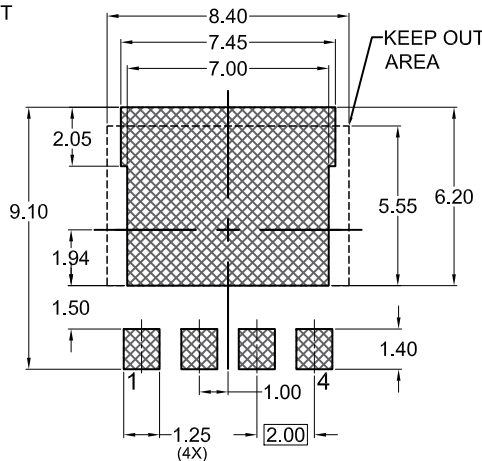
NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



RECOMMENDED LAND PATTERN

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



UNIVERSAL LAND PATTERN*

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.82	0.92	1.02
A1	0.00	—	0.05
b	0.90	1.00	1.10
b1	0.35	0.45	0.55
c	0.23	0.28	0.33
D	8.20	8.30	8.40
D1	8.00 BSC		
D2	6.80	6.90	7.00
D3	6.90	7.00	7.10
D4	4.90	5.05	5.20
D5	1.85 REF		
E	8.30	8.40	8.50
E1	7.90 BSC		
E2	5.24	5.34	5.44
E3	0.25	0.35	0.45
E4	6.08	6.23	6.38
E5	1.13 REF		
e	2.00 BSC		
e/2	1.00 BSC		
e1	2.70 BSC		
e1/2	1.35 BSC		
K	1.50	1.57	1.70
L	0.64	0.74	0.84
L1	0.67	0.77	0.87
Θ	0°	—	12°

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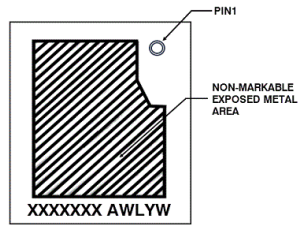
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TDFNW8 8.30x8.40x0.92, 2.00P
CASE 507AR
ISSUE C

DATE 29 MAY 2024

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot Code
Y = Year Code
W = Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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